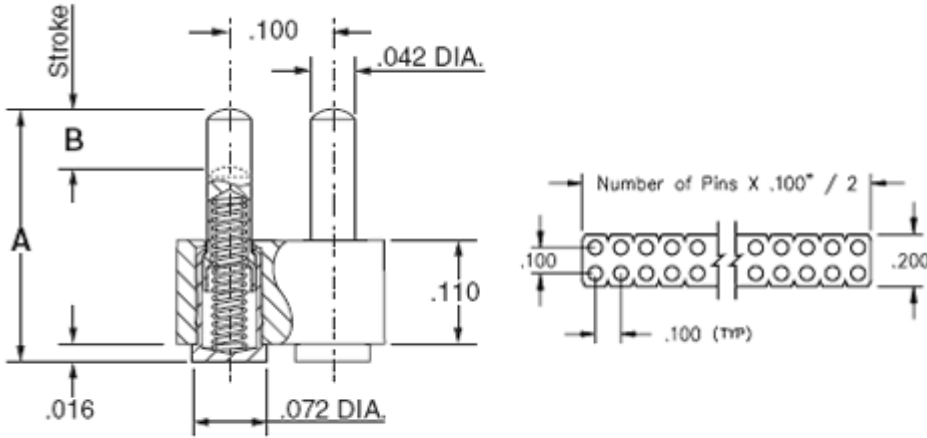




Product Number: 813-22-008-30-001101



**Description:**

Interconnect Header  
Spring-Loaded Header  
Initial Height of .177  
Double Row  
Surface Mount

**Plating Code:**

22

**Shell Plating:**

20 μ" Gold over 100 μ" Nickel

**Packaging:**

Packaged in Bulk

# Of Pins	A	B	Mill-Max Part Number	RoHS Compliant
8	0.177	0.045	813-22-008-30-001101	

**LOOSE PIN:**

Loose Pin Used: 0900

**BRASS ALLOY** (UNS C36000) per ASTM B 16

**Properties of BRASS ALLOY:**

- Chemical composition: Cu 61.5%, Zn 35.4%, Pb 3.1%†
- Hardness as machined: 80-90 Rockwell B
- Density: .307 lbs/in<sup>3</sup>
- Electrical conductivity: 26% IACS\*
- Melting point: 900°C/885°C (liquidus/solidus)

†(3 to 4% lead is used to permit "free machining" and is permitted by EC Directive 2002/95Annex 6; so all pin materials are RoHS compliant)

\*International Annealed Copper Standard, i.e. as a % of pure copper.

**INSULATOR INFORMATION:**

**PCT Polyester**, (Thermx CG933, black)

High Temperature

**Properties of PCT Polyester:**

- Brand: Thermx
- Grade: CG-933

- Rated voltage: 100 VRMS/150 VDC
- Insulation resistance: 10,000 Megaohms min.
- Material Heat Deflection Temp (per ASTM D 648): 529°F (276°C) @ 66 psi
- Dielectric strength: 1000 VRMS min. (700 VRMS min. for series 117 Shrink DIP)

Note: Materials above 446°F (230°C) are considered suitable for "eutectic" reflow soldering, above 500°F (260°C) for "lead-free" reflow soldering.